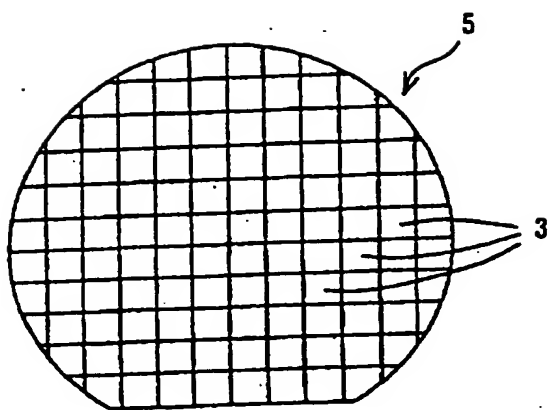
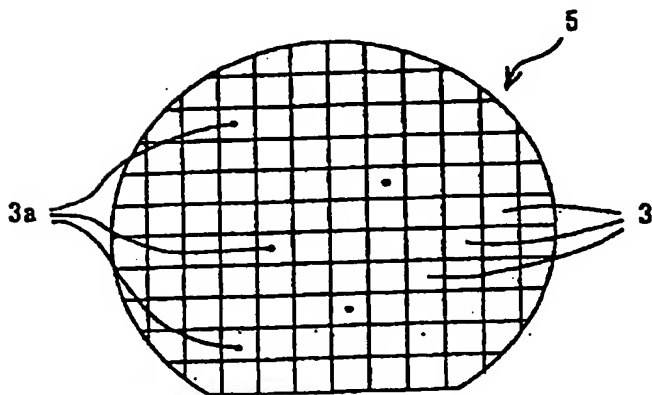


**Fig. 1**



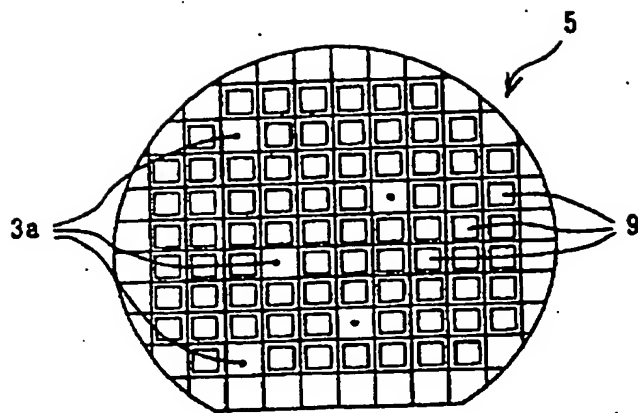
**3: Semiconductor chip forming section**  
**5: Semiconductor wafer**

**Fig. 2**



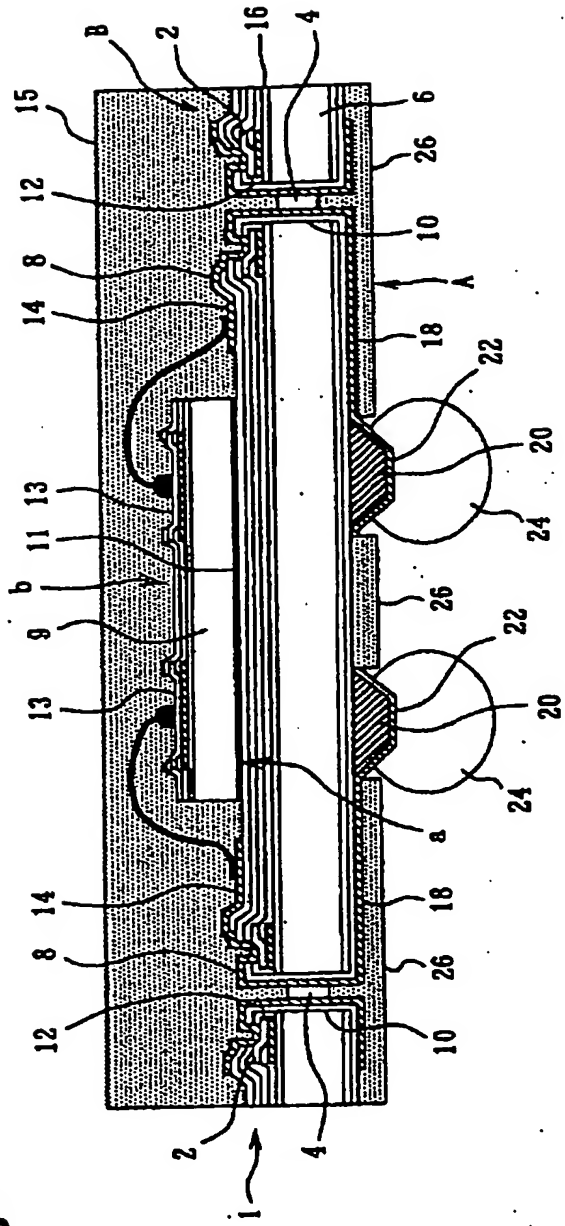
**3a: "BAD" mark**

**Fig. 3**



**9: Segmented other semiconductor chips**

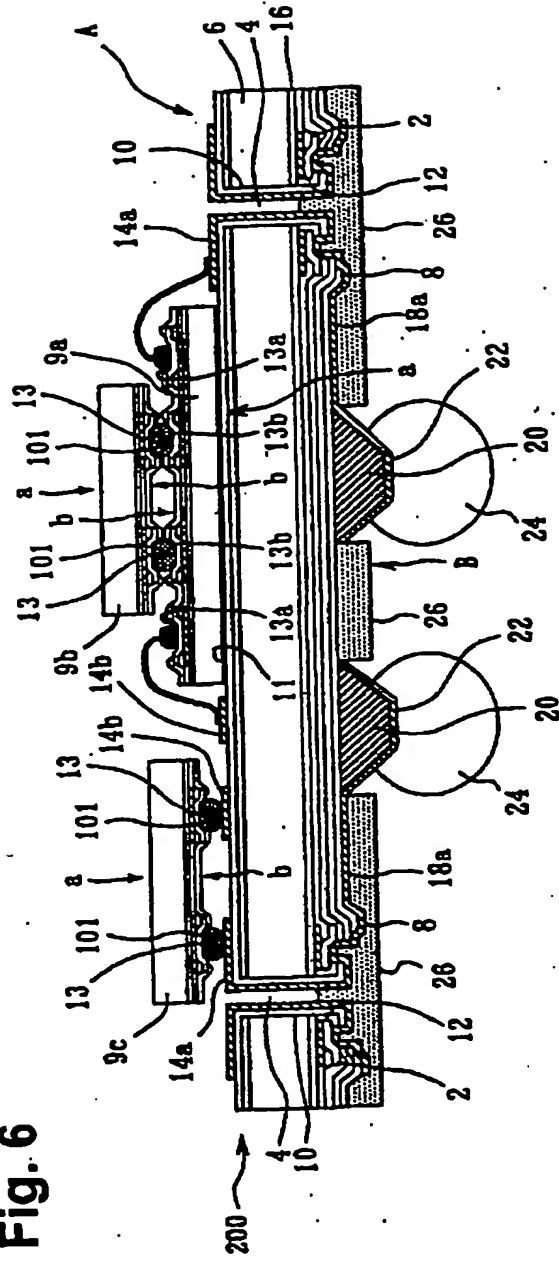
**Fig. 4**



- |                         |                                      |
|-------------------------|--------------------------------------|
| 1: Semiconductor device | 15: Protection layer                 |
| 2: Electrode            | 20: Stress relieving layer           |
| 4: Through hole         | 24: Solder ball (external electrode) |
| 8: Conduction layer     |                                      |

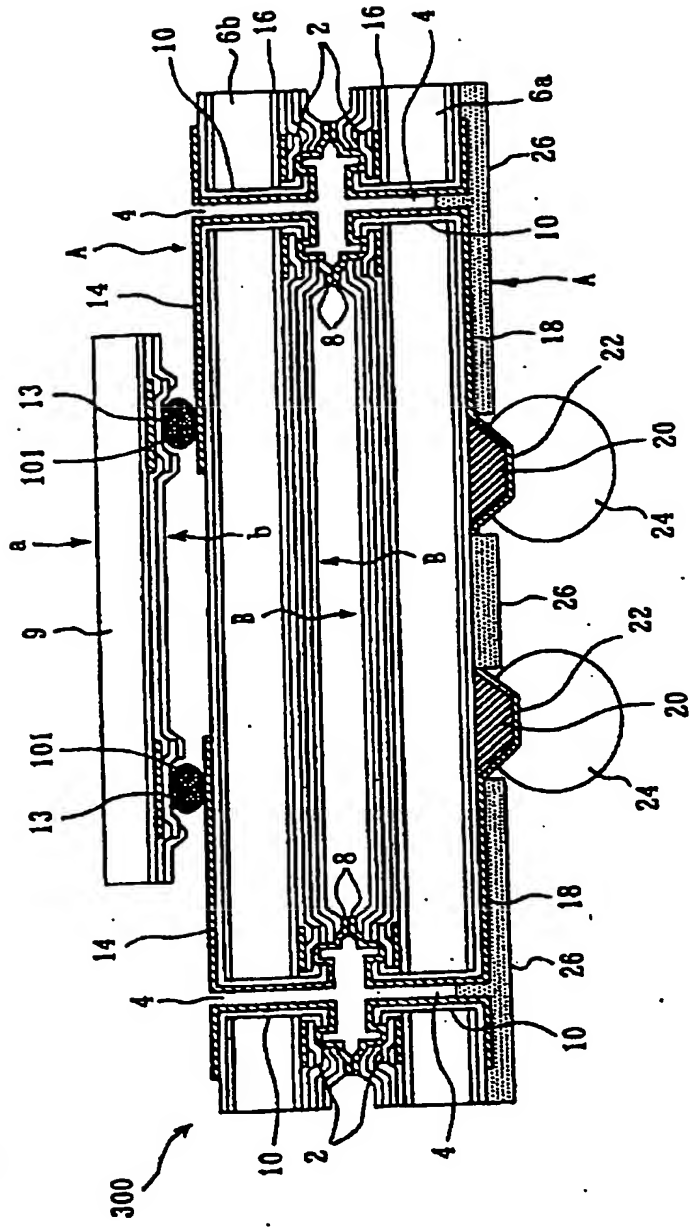
## 100: Semiconductor device

**Fig. 6**



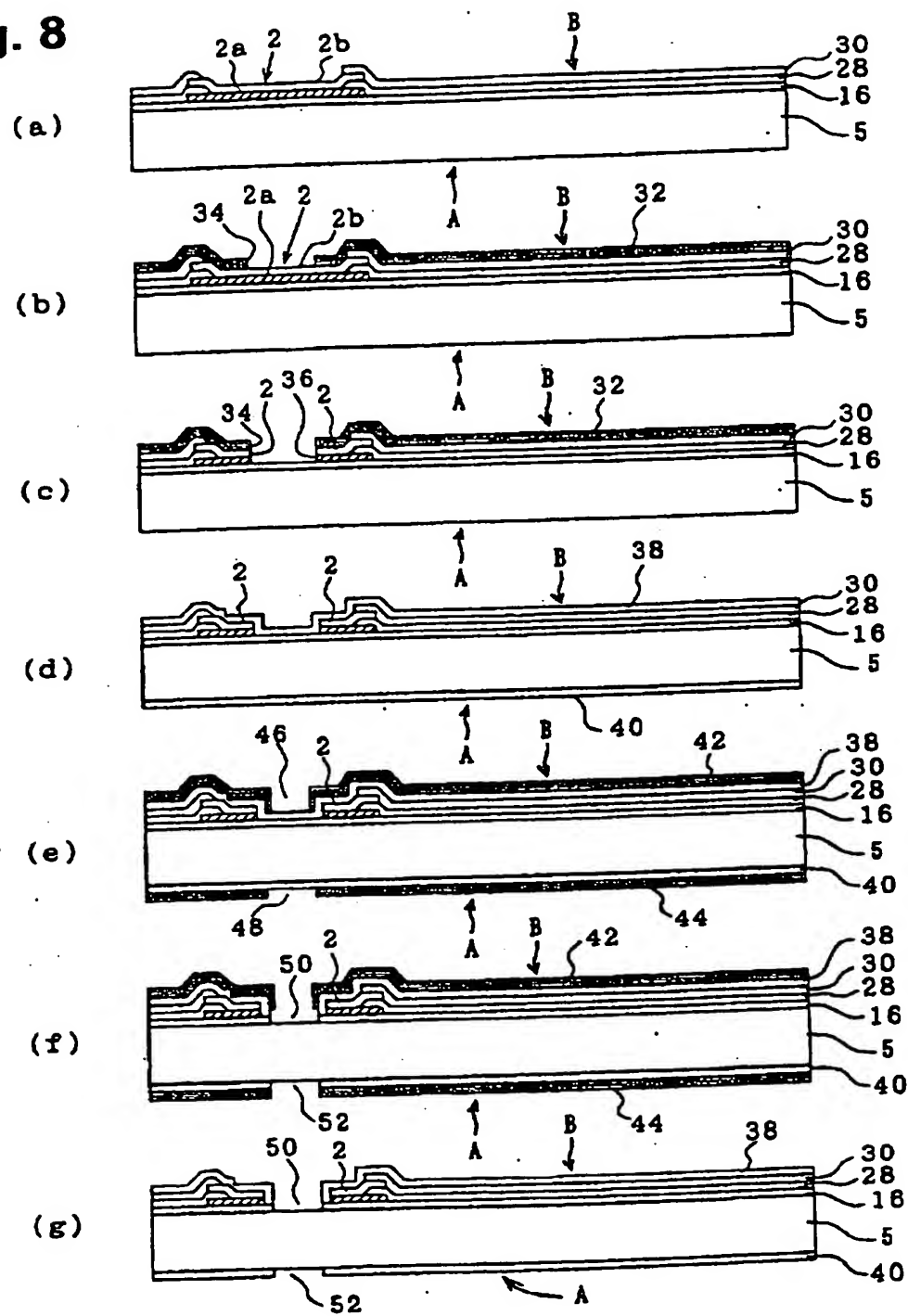
9a, 9b, 9c : Segmented other semiconductor chips  
 200 : Semiconductor device

Fig. 7

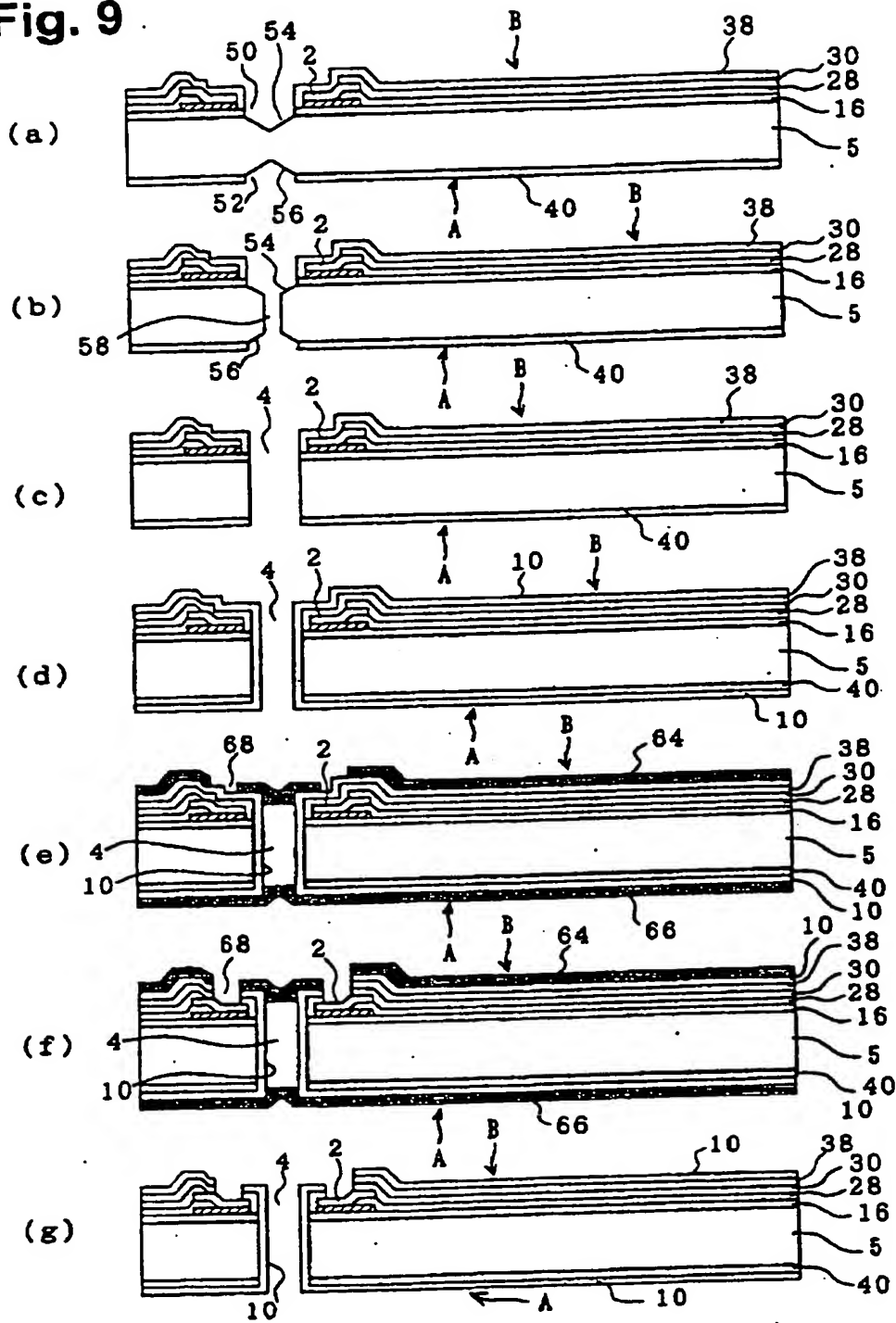


6b: Segmented another semiconductor chip  
300 : Semiconductor device

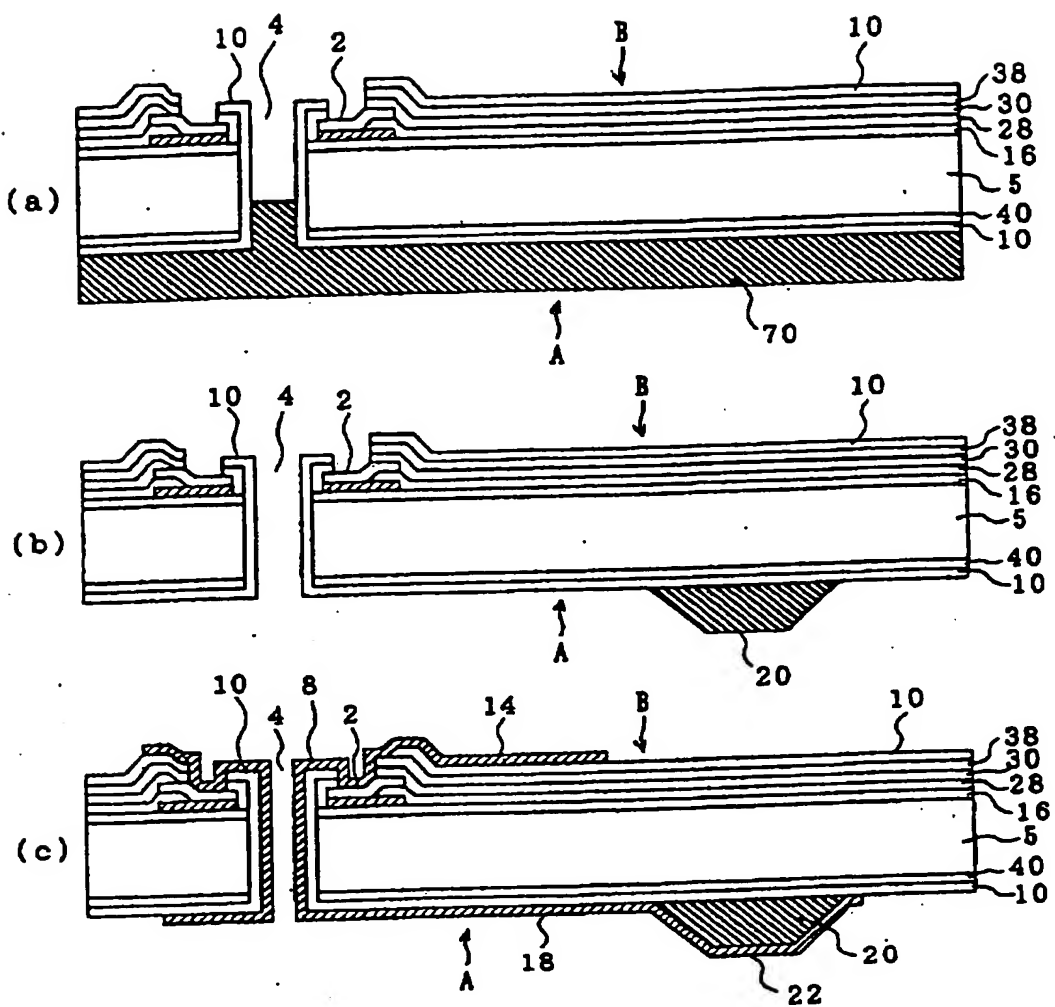
**Fig. 8**



**Fig. 9**







**Fig. 11**

